

LITHOGRAPHY SYSTEM, METHOD OF HEAT DISSIPATION AND FRAME**Abstract**

5 The present invention relates to a lithography system for projection an image or an image pattern on to a target such as a wafer. Energy that is accumulated in the target by the projection of the image or image pattern is removed from said target, such that expansion by local and/or overall heating is limited to a relevant pre-defined value, and wherein such heat removal is realized by the use of a phase transition in a heat absorbing material that is
10 brought into thermal contact with said target. As a further elaboration, such material may be applied in combination with a further material having a superior coefficient of heat transport, and may be incorporated in an emulsion comprising a material having a superior coefficient of heat transfer. Said material may e.g. be adhered to a bottom face of the target, and may also be included in a frame.

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FIG. 3